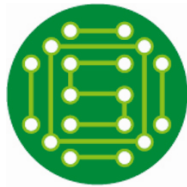


TECHNICAL CAPABILITY		Standard (2010)		Advanced (2010)		Roadmap (2011)	
		µm	mils	µm	mils	µm	mils
INNER LAYER	Tracks	50	2	25	1	20	0.8
	Insulation	50	2	25	1	20	0.8
OUTER LAYER	Tracks	75	3	50	2	25	1
	Insulation	75	3	50	2	25	1
LASER VIA PADS	External	250	10	200	8	180	7.2
	Internal	250	10	200	8	180	7.2
MECHANICAL VIA PADS	External	450	18	300	12	200	8
	Internal	500	20	400	16	250	10
ASPECT RATIO	Blind Vias	1:1		1:1		1:1.1	
	Through holes	1:11		1:12		1:13	
SOLDER GAP		38	1.5	25	1	20	0.8



TECHNICAL CAPABILITY

COPPER THICKNESS	Inner	12÷210 µm (1/3÷6 oz)
	Outer	3÷140 µm (1/12÷4 oz)
MIN DIELECTRIC THICKNESS	Inner	50 µm (2 mils)
	Outer	50 µm (2 mils)
HDI		4+N+4
MAX PANEL SIZE		640 X 540 mm (25"x 21")
MAX PANEL THICKNESS		4.2 mm (165 mils)
MAX LAYER COUNT		36 layers
MIN DIAM MECHANICAL HOLE		100 µm (4 mils)
MIN DIAM LASER VIA		75 µm (3 mils)
MECHANICAL DEPTH CONTROL		+/- 10 µm (+/- 4 mils)
IMPEDANCE CONTROL		+/- 7%

TECHNICAL CAPABILITY

Finishes

ENIG - Electroless Nickel Immersion Gold

ENEPIG - Electroless Nickel Electroless Palladium

OSP - Organic Solderability Preservative

HAL/HASL Sn/Pb - Hot Air Levelling

HAL/HASL Lead Free - Hot Air Levelling

Immersion Tin

Immersion Silver

Electrolytic Gold

Mixed Finishes (ex: OSP and chemical Gold, electrolytic Gold and chemical Gold, HAL and electrolytic Gold)

TECHNICAL CAPABILITY

Materials
(Lead, Lead Free,
Halogen Free)

ISOLA & ITEQ FR4 (Standard & High Tg)

SHENGYI (Standard & High Tg)

HITACHI (Standard & High Tg)

ARLON Polyimide & Thermount

NELCO PTFE

TACONIC PTFE

PANASONIC Lead & Halogen Free

MITSUBISHI High Tg

ROGERS